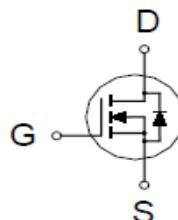
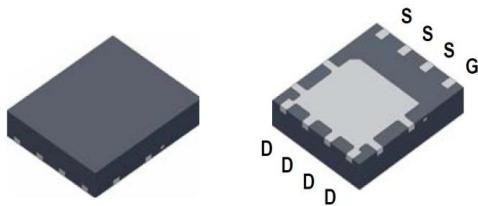


PK696BA

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

V _{(BR)DSS}	R _{DS(ON)}	I _D
30V	6mΩ @ V _{GS} = 10V	53A



PDFN 5X6P

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ³	I _D	53	A
T _c = 100 °C	I _D	34	
Pulsed Drain Current ¹	I _{DM}	150	
Continuous Drain Current	I _D	14	W
T _A = 70 °C	I _D	11	
Avalanche Current	I _{AS}	29	
Avalanche Energy	E _{AS}	42	mJ
Power Dissipation	P _D	31	W
T _C = 100 °C	P _D	12	
Power Dissipation	P _D	2.2	W
T _A = 70 °C	P _D	1.4	
Operating Junction & Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	R _{θJA}		56	°C / W
Junction-to-Case	R _{θJC}		4	

¹Pulse width limited by maximum junction temperature.

²The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C.

³Package limitation current is 20A.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.75	2.3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 14\text{A}$		5.2	8.5	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 14\text{A}$		4	6	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 14\text{A}$		62		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		1228		pF
Output Capacitance	C_{oss}			212		
Reverse Transfer Capacitance	C_{rss}			154		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.6		Ω
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 14\text{A}$		28		nC
				15		
Gate-Source Charge ²	Q_{gs}			3.1		
Gate-Drain Charge ²	Q_{gd}			8.2		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 15\text{V}, I_D \geq 14\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		18		nS
Rise Time ²	t_r			10		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			39		
Fall Time ²	t_f			11		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				25	A
Forward Voltage ¹	V_{SD}	$I_F = 14\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 14\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		26		nS
Reverse Recovery Charge	Q_{rr}			13		nC

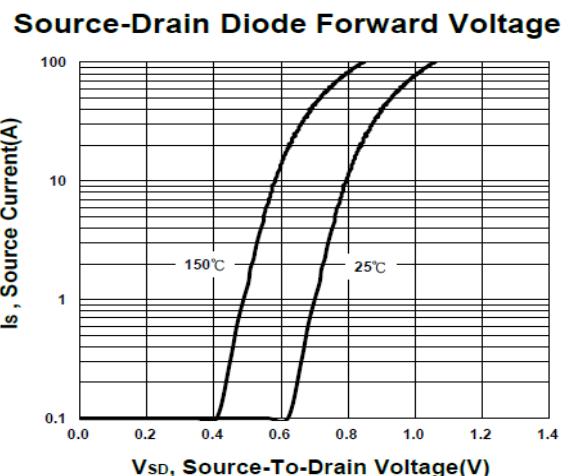
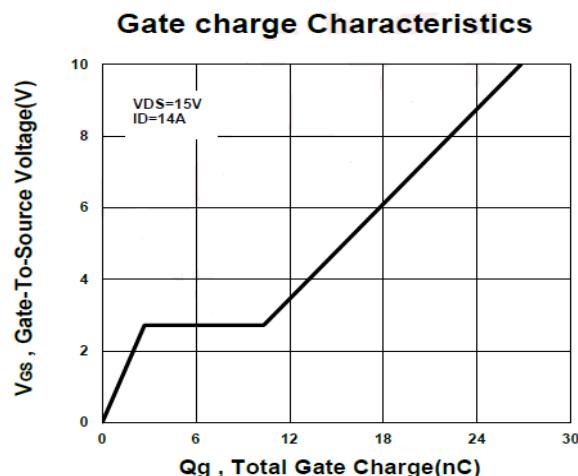
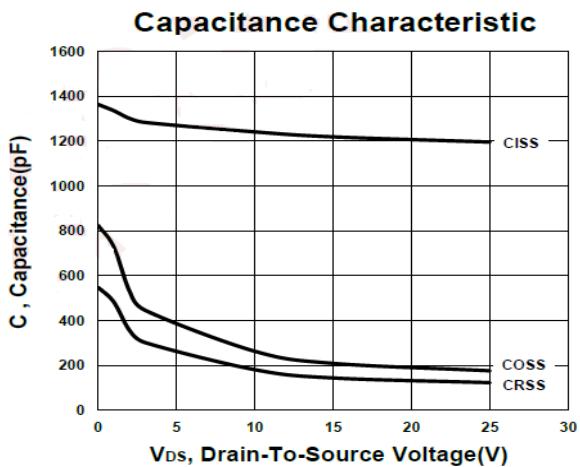
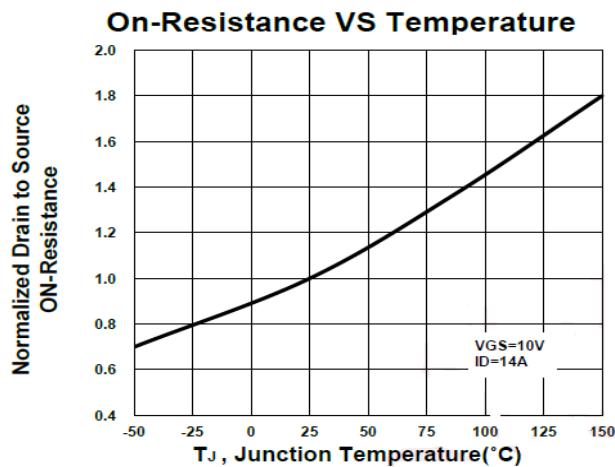
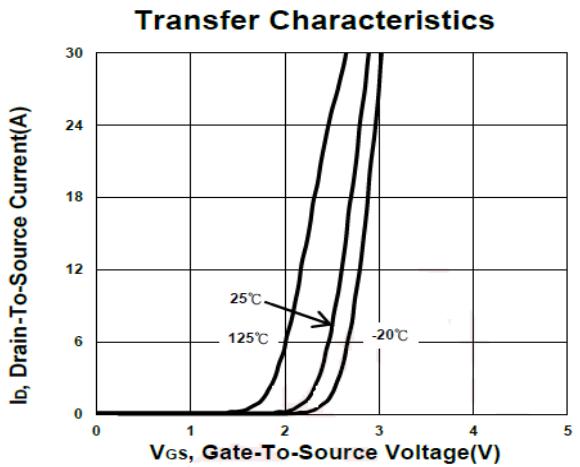
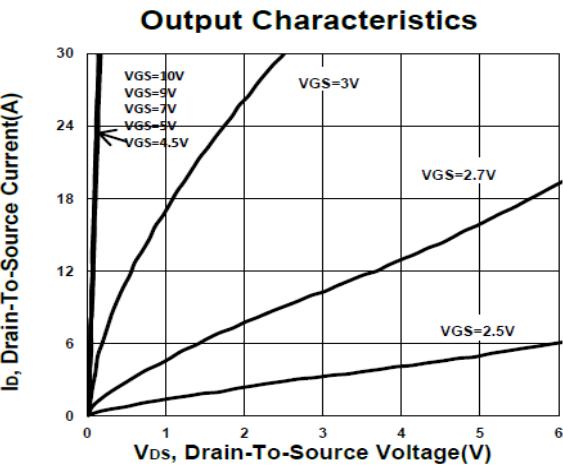
¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Package limitation current is 20A.

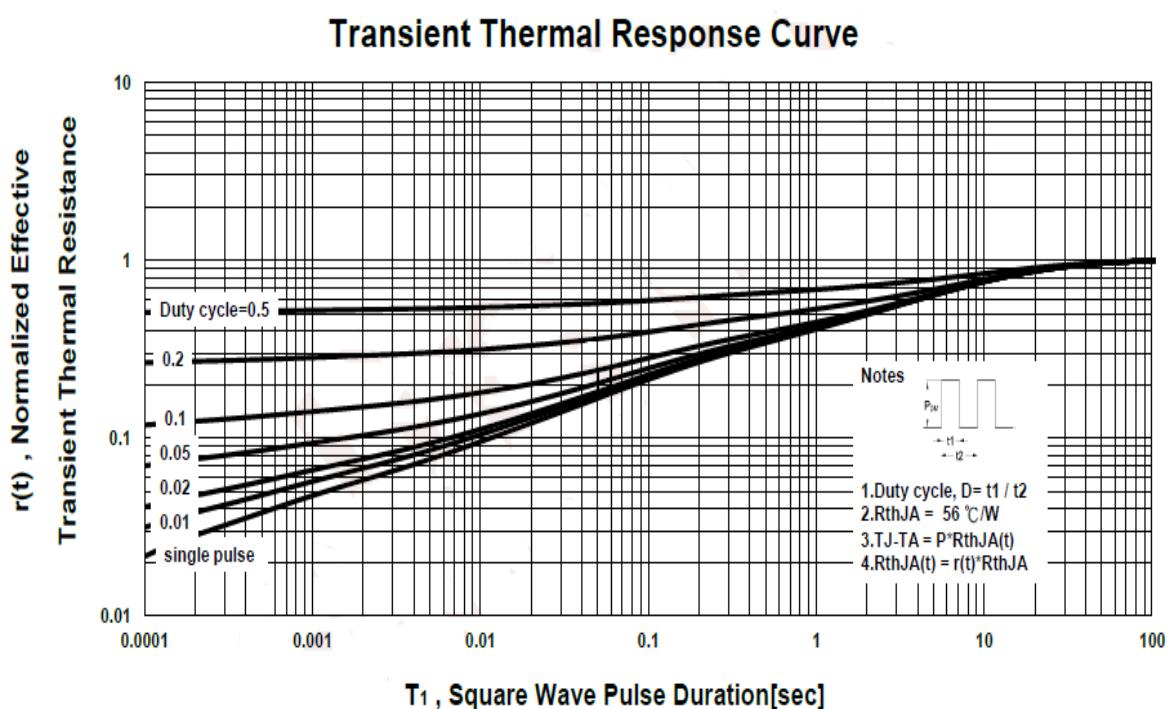
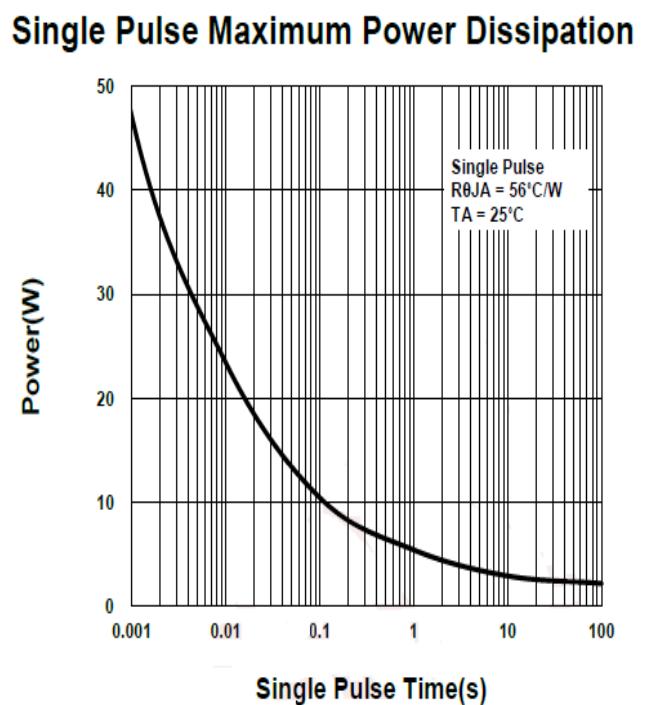
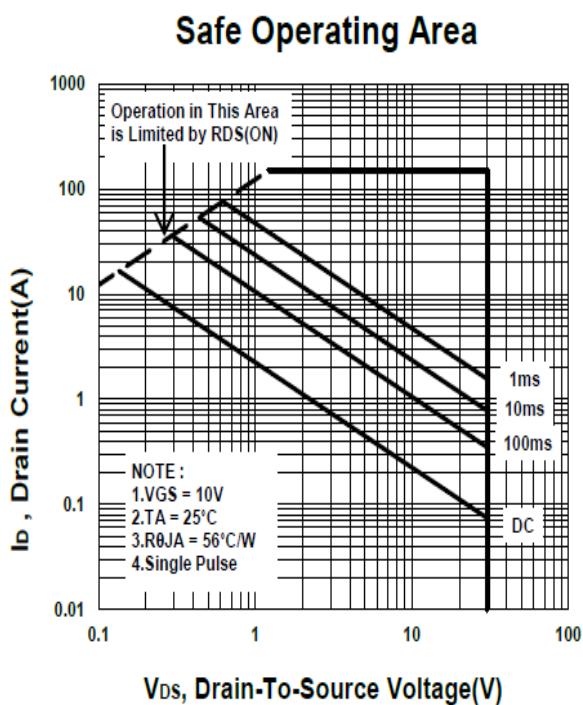
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PDFN 5x6P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8		5.15	J	3.33		3.78
B	5.44		5.9	K	0.9		
C	5.9		6.35	L	0.35		0.712
D	0.33		0.51	M	0°		12°
E		1.27		N	4.8		5.5
F	0.8		1.25	O	0.05		0.3
G	0.15		0.34	P	0.06		0.2
H	3.61		4.31	S	3.69		4.19
I	0.35		0.71				

